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B/O FORM PTO-1695 (1/31/92)	U.S. Department of Commerce
Petent and Trademark Office RECORDATION FORM COVER SHEET PATENTS ONLY	
To the Honorable Commissioner of Patents and Trademarks.	Please record the attached original documents or copy thereof.
1. Name of Conveying Party:	2. Name and Address of Receiving Party(ies):
1) Wen-Kun YANG 2) Wen-Pin YANG 3) Shih-Li CHEN	Name: Advanced Chip Engineering Technology Inc.
G Additional names of conveying parties attached.	Street Address: No. 65, Guangfu N. Rd., Hukou shiang,
3. Nature of Conveyance X Assignment Merger Security Agreement Change of Name Other:	City, State, Zip: Hsinchu, TAIWAN 303, R.O.C.
Execution Date: 1) December 8, 2003 2) December 12, 2003 3) December 11, 2003	G Additional name(s) and address(es) attached.
4. (A) Patent Application Number(s):	4. (B) Patent Number(s):
10/725,933	
If this document is being filed together with a new application, the execution date of the application is: Additional Numbers Attached.	6. Total Number of Applications and Patents Involved:
5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed:	
Name: Gary M. Nath	7. Total Fee:
Address: NATH & ASSOCIATES PLLC 1030 15 th Street, N.W. B 6 th Floor Washington, D.C. 20005	(37 CFR 3.41) \$ 40.00 Enclosed. X Authorized to be charged to deposit account .
	8. Deposit Account Number: 14-0112 ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT.
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9. Statement and Signature: To the best of my knowledge and belief, the copy is a true copy of the original document	
Name of Person Signing Bary M. Neth, Reg. Marvin C. Berkowit	z, Reg. No. 47,421
Attorney Docket No.: 25857 Customer N	io. 20529
Total number of pages comprising cover sheet: 1	

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PATENT Attorney Docket No.: 2.5857

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION given to Wen-Kun Yang, Wen-Pin Yang, Shih-Li Chen, hereinafter referred to as the ASSIGNOR(S), who has/have invented certain new and useful Fan Out Type Wafer Level Package Structure and Method of the Same, hereinafter referred to as the invention, for which I/we has/have executed an application for Letters Patent to be filed in the United States Patent and Trademark Office.

WHEREAS, Advanced Chip Engineering Technology Inc., a corporation organized and existing under the laws of the country/state of Taiwan, whose post office address/business address is No. 65, Guangfu N. Rd., Hukou Shiang, Hsinchu, Taiwan 303, R.O.C., hereinafter referred to as the ASSIGNEE, desires to acquire the entire right, title and interest for the United States and elsewhere throughout the world in and to said invention and application, including any and all divisions and continuations thereof, all rights of priority under the terms of the International Convention for the Protection of Industrial Property, and any and all Letters Patent which may be granted thereof.

NOW, WITNESSETH THIS that for and in consideration of the sum of one dollar (\$1.00) and other good and valuable consideration, the receipt, adequacy and sufficiency of which are hereby acknowledged, said ASSIGNOR(S) hereby assign(s), sell(s) and transfer(s) to said ASSIGNEE, its assigns and legal representatives, the entire right, title and interest for the United States and elsewhere throughout the world, in and to said invention and application, including any and all divisions and continuations thereof, all rights of priority under the terms of the International Convention for the Protection of Industrial Property, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges, and advantages in any way arising from or pertaining thereto, for and during the term or terms of any and all such Letters Patent when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said ASSIGNEE and its assigns and legal representatives, in as ample

> PATENT REEL: 014279 FRAME: 0152

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and as beneficial a manner for all intents and purposes as said ASSIGNOR(S) might or could have held and enjoyed the same had this assignment not been made.

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PATENT Attorney Docket No.: **25857**

ASSIGNMENT

ALSO, said ASSIGNOR(S) hereby agree(s) to execute all papers necessary to file said applications in the United States and elsewhere throughout the world, and to assign the same to said ASSIGNEE, or any assignee acquiring title to said invention, and to execute any other papers that may be needed in connection with filing said application and securing any and all Letters Patent thereon.

AND said ASSIGNOR(S) authorize(s) and request(s) the Commissioner of Patents to issue a Letters Patent on said application, and on any and all divisions and continuations thereof, to said ASSIGNEE, its assigns and legal representatives, in accordance herewith.

By:

Inventor's Name: Wen-Kun Yang

(first or first inventor)

By:

12/12/63

1218103

Date

Inventor's Name: Wen-Pin Yang (second inventor)

Date

By:

Ship-li chen

Inventor's Name: Shih-Li Chen (third inventor)

Date

12/11/103

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RECORDED: 01/22/2004